

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
(213.003-US)

In re Application of: YE ET AL.

Serial No: 10/677,563

Filed: OCTOBER 2, 2003

Title: METHOD AND APPARATUS FOR MONITORING
INTEGRATED CIRCUIT FABRICATION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

) Group Art Unit:

) Examiner:

I hereby certify that this
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Michiko Sitee
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SECOND INFORMATION DISCLOSURE STATEMENT

Dear Sir:

Submitted herewith are three (3) sheets of a modified Form PTO-1449. A copy of
each document cited on the attached Form PTO-1449 is also submitted.

It is respectfully requested that the Examiner make his/her consideration of these
documents formally of record with the initial Office Action.

Respectfully submitted,

Neil A. Steinberg
Reg. No. 34,735
650-968-8079

Date: January 20, 2004

PTO-1449 (Modified) U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO. 22 2004 213.003-US	SERIAL NUMBER 10/677,563
	APPLICANT(S) Ye et al.	
	FILING DATE October 2, 2003	GROUP ART UNIT

U.S. PATENT DOCUMENTS

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE

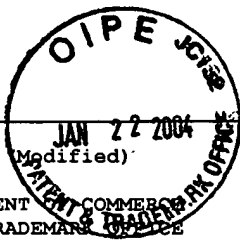
FOREIGN PATENT DOCUMENTS

EXAMINER INITIALS	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION YES/NO
	EP 0 628 806	4/1994	European			
	WO 00/59206	10/2000	PCT			
	WO 02/17030	2/2002	PCT			

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	"A New Mask Evaluation Tool, the Microlithography Simulation Microscope Aerial Image Measurement System", Budd, et al., SPIE Vol. 2197, 1994, pp.530-540
	"Characterization of Lithographic System Performance Through Direct Aerial Image Measurements", C.H. Fields, SRC/SEMATECH, 1996 (96-MC-500)
	"Aerial Image Measurements on a Commercial Stepper", Fields, et al., SPIE Vol. 2197, 1994, pp.585-595
	"A Novel High-Resolution Large-Field Scan-and-Repeat Projection Lithography System", K. Jain, SPIE Vol. 1463 Optical/Laser Microlithography IV, 1991, pp.666-677
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EXAMINER	DATE CONSIDERED
EXAMINER: Initial citation if reference was considered. Draw line through citation if not in conformance to MPEP 609 and not considered. Include copy of this form with next communication to applicant.	



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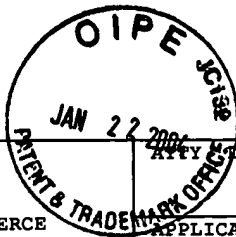
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	"Optical Limitations to Cell Size Reduction in IT-CCD Image Sensors", Satoh et al., IEEE, Transactions on Electron Devices, Vol. 44, No. 10, Oct. 1997, pp.1599-1603
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